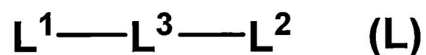


ABSTRACT

Provided are a method for cleaning a semiconductor substrate that can cleanly remove (clean) an adhesive layer obtained using, for example, a siloxane-based adhesive from a semiconductor substrate having the adhesive layer on a surface thereof in a shorter time by a simple operation, a method for manufacturing a processed semiconductor substrate including such a cleaning method, and a composition used in such a cleaning method.

A method for cleaning a semiconductor substrate includes a step of peeling and dissolving an adhesive layer formed on a semiconductor substrate using a peeling and dissolving composition, in which the peeling and dissolving composition contains: a component [I]: a quaternary ammonium salt; a component [II]: an amide-based solvent; and a component [III]: a solvent represented by the following Formula (L):



(in the formula, L^1 and L^2 each independently represent an alkyl group having 2 to 5 carbon atoms, and L^3 represents O or S).

[No figure]